

## AMENDMENTS TO THE CLAIMS

- 1. (Currently Amended)** A semiconductor manufacturing device comprising:

  - a processing chamber;
  - a supply passage ~~that supplies~~ for supplying a processing gas to an inside of the processing chamber;
  - a transferring passage through which a wafer is to be put [[in]] into and taken out of the processing chamber;
  - an exhaust passage through which the processing gas inside the processing chamber is to be exhausted; and
  - a sheet-like heating unit ~~that in order~~ arranged to heat an inner wall face of at least one of the supply passage, the transferring passage, the processing chamber, and the exhaust passage, ~~sandwiches and covers~~ including a thin plate-shaped resistive heating element sandwiched and covered by a pair of metal plates, the heating unit being arranged so as to detachably cover ~~and covers~~ the inner wall face from an inner side of the at least one of the supply passage, the transferring passage, the processing chamber and the exhaust passage, a portion of the metal plates extending to an outside of the semiconductor manufacturing device, wherein a space between the metal plates in a region of the metal plates which is to be exposed to the processing gas is sealed with a spacer at edges of the metal plates in the region to be exposed to the processing gas, and wherein edges of the portion of the metal plates which extends to the outside are open to the outside.

- 2. (Currently Amended)** The semiconductor manufacturing device as set forth in Claim 1, wherein the heating unit includes a heating main body to be disposed adjacent to the inner wall face, wherein the portion of the metal plates which extends to the outside comprises an attaching portion formed into a flange shape or so as to extend integrally with the heating main body, and wherein the heating unit includes a connector that is provided at the attaching portion to draw out

a wire for conducting electricity to the resistive heating element and a wire of a temperature sensor ~~that detects~~ for detecting a temperature of the resistive heating element.

**3. (Withdrawn)** The semiconductor manufacturing device as set forth in Claim 2, wherein

a piping defining the exhaust passage is formed of a plurality of pipes that are formed to be attachable and detachable and joined to each other,

the plurality of pipes have sword guard-shaped flange portions that project radially outward and face each other, at connection ends, and

the attaching portion of the heating unit is sandwiched by the flange portions via a sealing member.

**4. (Withdrawn – Currently Amended)** The semiconductor manufacturing device as set forth in Claim 3, further comprising:

a clamp mechanism for joining the flange portions of the plurality of pipes,

wherein the clamp mechanism has a plurality of clamp blocks having grooves with roughly V-shaped sections to receive the flange portions so as to press the flange portions closer to each other, a plurality of link plates that link the plurality of clamp blocks, and a fastening member that ~~fasten the~~ fastens two adjacent clamp blocks.

**5. (Withdrawn – Currently Amended)** The semiconductor manufacturing device as set forth in Claim 4, wherein

the plurality of link plates ~~include~~ includes a plurality of first link plates that link ~~one~~ first side portions of the clamp blocks to each other, respectively, and a plurality of second link plates that link ~~the other~~ second side portions of the clamp blocks to each other, respectively, and

at least one link plate of the first link plates and the second link plates is formed so as to be latched on and released from one of the clamp blocks.

**6. (Currently Amended)** A heating unit [[of]] for heating, in a semiconductor manufacturing device, ~~which heats~~ an inner wall face of any at least one of a processing chamber, a transferring passage through which a wafer is to be put [[in]] into and taken out of the processing chamber, and an exhaust passage through which a processing gas inside the processing chamber is to be exhausted, comprising:

a thin plate-shaped resistive heating element; and

a pair of metal plates that are formed to sandwich and cover the resistive heating element, the metal plates being arranged so as to detachably cover like a sheet the inner wall face from an inner side of the at least one of the processing chamber, the transferring passage and the exhaust passage, and so as to define the at least one of the processing chamber, the transferring passage and the exhaust passage, or the passages a portion of the metal plates being arranged to extend to an outside of the semiconductor manufacturing device, wherein a space between the metal plates in a region of the metal plates which is to be exposed to the processing gas is sealed with a spacer at edges of the metal plates in the region to be exposed to the processing gas, and wherein edges of the portion of the metal plates which is to extend to the outside are open to the outside.

**7. (Currently Amended)** The heating unit of a semiconductor manufacturing device as set forth in Claim 6, wherein the heating unit includes a heating main body ~~that is to be~~ disposed adjacent to the inner wall face, wherein the portion of the metal plates which is to extend to the outside comprises an attaching portion formed into a flange shape or to extend integrally with the heating main body, and wherein the heating unit includes a connector that is provided at the attaching portion so as to draw out a wire for conducting electricity to the resistive heating element and a wire of a temperature sensor ~~that detects~~ for detecting a temperature of the resistive heating element.

**8. (Currently Amended)** The heating unit of a semiconductor manufacturing device as set forth in Claim 7, wherein

the heating unit includes a chamber heating unit ~~that is to be~~ disposed adjacent to the inner wall face of the processing chamber, and

the chamber heating unit includes a cylindrical heating main body to be disposed adjacent to a side wall face of the processing chamber and an attaching portion provided in a flange shape at an end of the heating main body, and a disk-shaped heating main body to be disposed to face a bottom wall face of the processing chamber and an attaching portion provided to extend on a lower face of the heating main body.

**9. (Withdrawn – Currently Amended)** The heating unit ~~of a semiconductor manufacturing device~~ as set forth in Claim 7, wherein

the heating unit includes a chamber heating unit to be disposed adjacent to an inner wall face of the processing chamber, and

the chamber heating unit includes a cylindrical heating main body having a bottom wall and an attaching portion provided in a flange shape at an opening end of the heating main body.

**10. (Currently Amended)** The heating unit ~~of a semiconductor manufacturing device~~ as set forth in Claim 7, wherein

the heating unit includes a transferring passage heating unit ~~that is to be~~ disposed adjacent to an inner wall face of the transferring passage, and

the transferring passage heating unit includes a cylindrical heating main body having a roughly rectangular section and an attaching portion provided in a flange shape on the heating main body.

**11. (Currently Amended)** The heating unit ~~of a semiconductor manufacturing device~~ as set forth in Claim 7, wherein

the heating unit includes an exhaust passage heating unit to be disposed adjacent to an inner wall face of the exhaust passage, and

the exhaust passage heating unit includes a cylindrical heating main body and an attaching portion provided in a flange shape on the heating main body.

**12. (Withdrawn – Currently Amended)** The heating unit ~~of a semiconductor~~

~~manufacturing device~~ as set forth in Claim 7, wherein

the heating unit includes an exhaust passage heating unit to be disposed adjacent to an inner wall face of a curved exhaust passage,

the exhaust passage heating unit includes a curved cylindrical heating main body and an attaching portion provided in a flange shape on the heating main body, and

the heating main body is formed so that a heating value becomes higher in an outside region than in an inside region of the curved exhaust passage.

**13. (Currently Amended)** The heating unit ~~of a semiconductor manufacturing device~~ as set forth in Claim 7, wherein the heating unit is to be disposed by leaving so as to define a space for insulating heat between the heating unit and the inner wall face.